**GEG121022: Board Resolution**

On May 30, 2024, Corporate bond of Gia Lai Electricity Joint Stock Company announced Resolution No. 16A/2024/TYNQ-HDQT on approving the issuance of private bonds, approving the plan on issuing private bonds of Gia Lai Electricity Joint Stock Company in 2024 (Expected bond codes GEGH2429001 and GEGH2429002), and registering bond trading on the private bond trading system at the Hanoi Stock Exchange as follows:

‎‎Article 1. Approve issuing private bonds in 2024 of the Company and approve the plan on issuing private bonds in 2024 of the Company:

1. Issuer: Gia Lai Electricity Joint Stock Company
2. Bond name: Gia Lai Electricity Joint Stock Company’s bonds
3. Expected bond code:
* 1st issuance: GEGH2429001
* 2nd issuance: GEGH2429002
1. Issuance purpose: Restructuring the debt of the Issuer
2. Total value of issued bonds at par value: Maximum VND 300,000,000,000 (calculated according to par value), in which the value of issued Bonds of each Issuance is as follows:
* 1st issuance: Expected VND 100,000,000,000
* 2nd issuance: Expected VND 200,000,000,000
1. Type of bonds: Corporate bonds, non-convertible, without warrants, secured by assets.
2. Currency for issuance and payment: VND
3. Form of bonds: Bonds are issued under the form of accounting entry.
4. Bond par value: VND 100,000,000/bond
5. Issuance price: Equal to 100% of the par value of bonds
6. Bond term: 60 months
7. Number of issuance periods: 02 issuances
8. The bond distribution time of each offering does not exceed 30 days from the date of information disclosure before the offering. The total time for offering bonds in multiple rounds must not exceed 06 months from the issuance date of the first offering.
9. Expected issue date:
* 1st issuance: Expected in June - July 2024
* 2nd issuance: Expected in August - September 2024.
1. Payment method of bond principal and interest:
* Payment method of bond principal: The Bond principal will be paid once by the par value of bonds on the Maturity date unless the Bonds are redeemed before maturity according to the regulations in the Plan on Issuing Bond.
* Payment method of bond interest: Bond interest is paid later, periodically every 3 months on the Interest Payment Date.
1. Use assets owned by the Company and/or assets of other third parties as collateral for the Company's obligations related to the bonds stated in the Plan on Issuing Bond.
2. Bonds are registered for trading on the private bond trading system at the Hanoi Stock Exchange according to the current provisions of law.
3. Other detailed contents according to the Plan on Issuing Bond in 2024 according to Resolution No. 16/2024/NQ-HDQT dated May 30, 2024.

‎‎Article 2. Terms of enforcement

* This Resolution takes effect from the date of its signing.
* Members of the Board of Directors, the Executive Board, and all employees of the Company are responsible for the implementation of this Resolution.